

TMBAT49

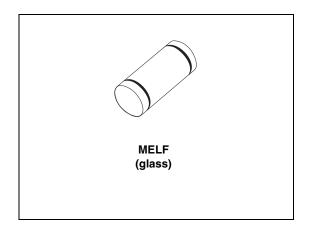
Small signal Schottky diode

Features

- very low turn-on voltage
- fast switching

Description

The TMBAT49 is a general purpose metal to silicon diode. This device has integrated protection against excessive voltage such as electrostatic discharges.



Characteristics TMBAT49

1 Characteristics

Table 1. Absolute ratings (limiting values)

Symbol	Parameter	Value	Unit
V _{RRM}	Repetitive peak reverse voltage	80	V
I _F	Forward continuous current	500	mA
I _{FRM}	Repetitive peak forward current	3	Α
I _{FSM}	Surge non repetitive forward current	10	Α
T _{stg}	Storage temperature range	- 65 to +150	°C
Tj	Operating junction temperature range	- 65 to +125	°C
T _L	Maximum lead soldering temperature during 15	260	°C

Table 2. Thermal parameter

Symbo	l Parameter	Value	Unit
R _{th(j-l)}	Junction to lead	110	°C/W

Table 3. Static electrical characteristics

Symbol	Parameter	Test conditions		Min.	Тур.	Max.	Unit
I _R ⁽¹⁾	Reverse leakage current	T _j = 25 °C	V _R = 80 V	-	-	200	μΑ
			I _F = 10 mA	-	-	0.32	
$V_F^{(1)}$	Forward voltage drop	T _j = 25 °C	I _F = 100 mA	-	-	0.42	V
			I _F = 1 A	-	-	1	

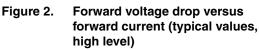
^{1.} Pulse test: $t_p \le 300 \ \mu s, \ \delta < 2\%$

Table 4. Dynamic characteristics $(T_i = 25 \text{ °C})$

Symbol	Parameter	Test conditions		Min.	Тур.	Max.	Unit
	Diode capacitance	E _ 1 MUz	V _R = 0 V	-	120	-	pF
	Diode capacitance	1 – 1 1011 12	V _R = 5 V	r _R = 5 V - 39	35	-	

TMBAT49 Characteristics

Figure 1. Forward voltage drop versus forward current (typical values, low level)



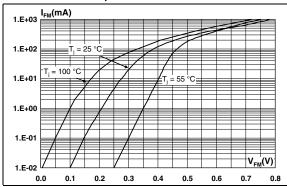
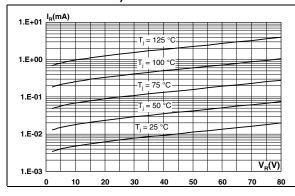


Figure 3. Reverse leakage current versus reverse voltage applied (typical values)

Figure 4. Junction capacitance versus reverse voltage applied (typical values)



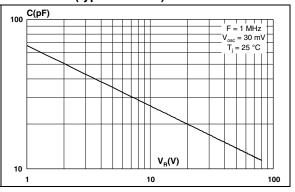
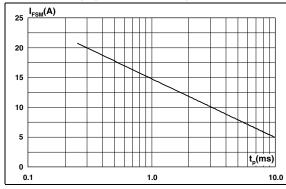
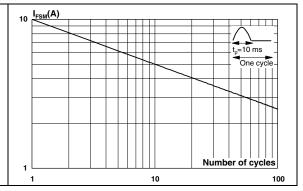


Figure 5. Non-repetitive peak surge forward Figure 6. current versus pulse duration (square waveform)

gure 6. Non-repetitive peak surge forward current versus number of cycles





Package information TMBAT49

2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: www.st.com. ECOPACK[®] is an ST trademark.

Table 5. MELF package dimensions

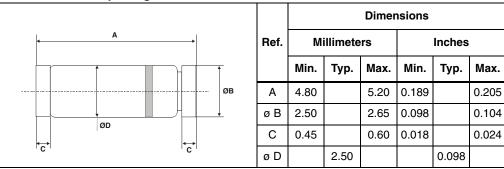
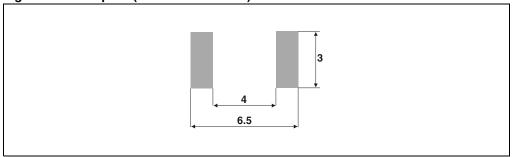


Figure 7. Footprint (dimensions in mm)



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3 Ordering information

Table 6. Ordering information

Order code	Marking	Package Weight		Base qty	Delivery mode
TMBAT49FILM	Cathode ring	MELF (glass)	0.15 g	1500	Bulk

4 Revision history

Table 7. Document revision history

Date Revision		Changes		
Aug-1999	1A	Previous release.		
12-Nov-2010 2		Added ECOPACK statement. Updated graphics in Section 1.		

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